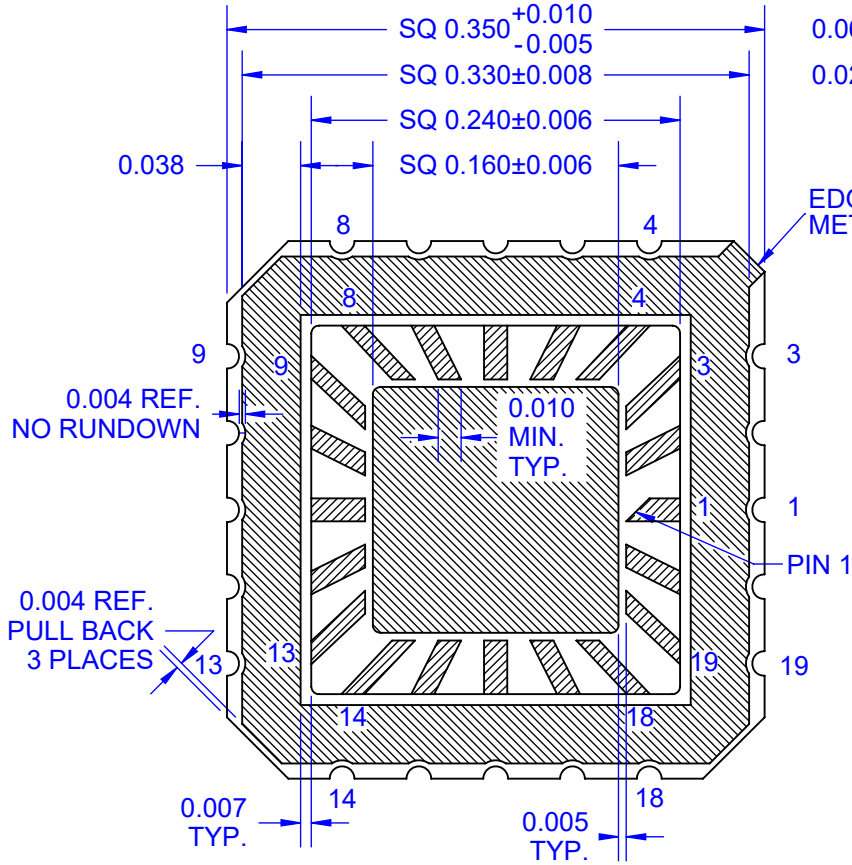
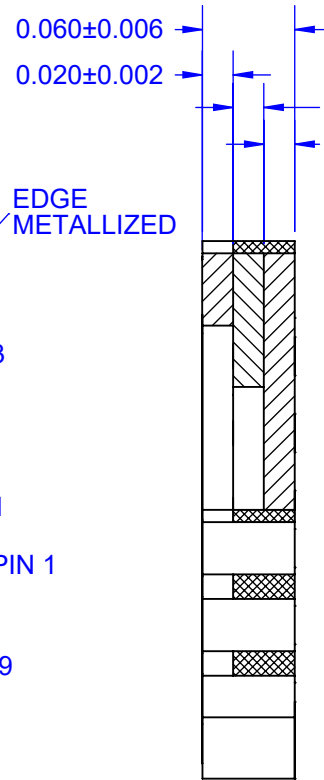


NON-MAGNETIC

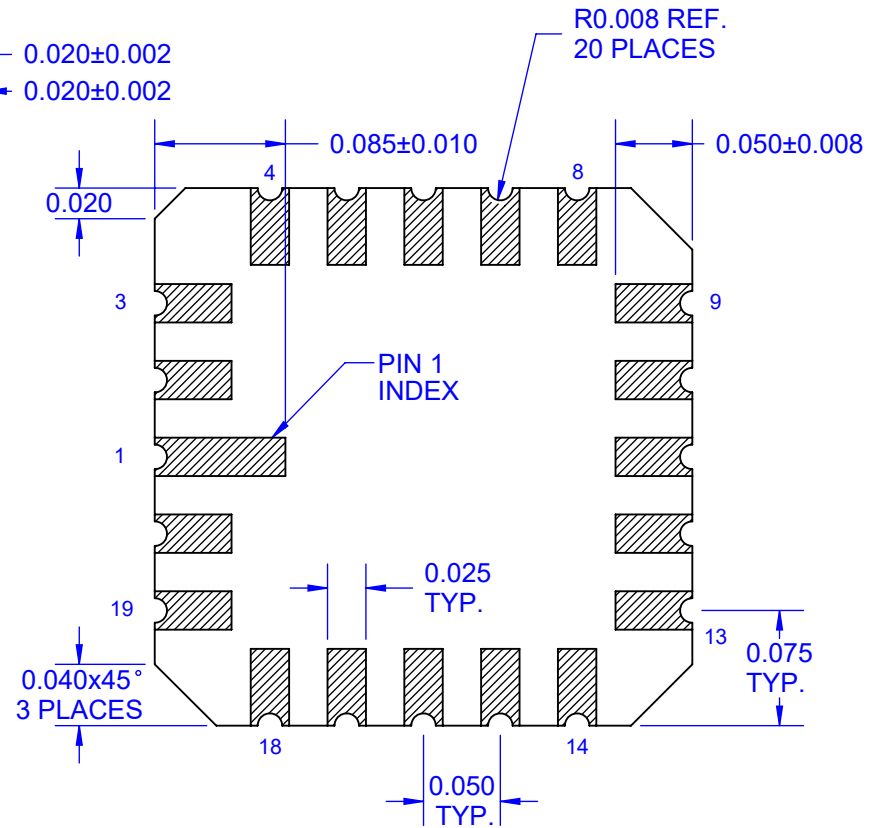
TOP VIEW



SIDE VIEW



BOTTOM VIEW



DIE PAD
0.160 x 0.160-inch
[4.06 x 4.06mm]

NOTES: (Unless Otherwise Specified).

1) DIMENSION in INCH.

2) PLATING:

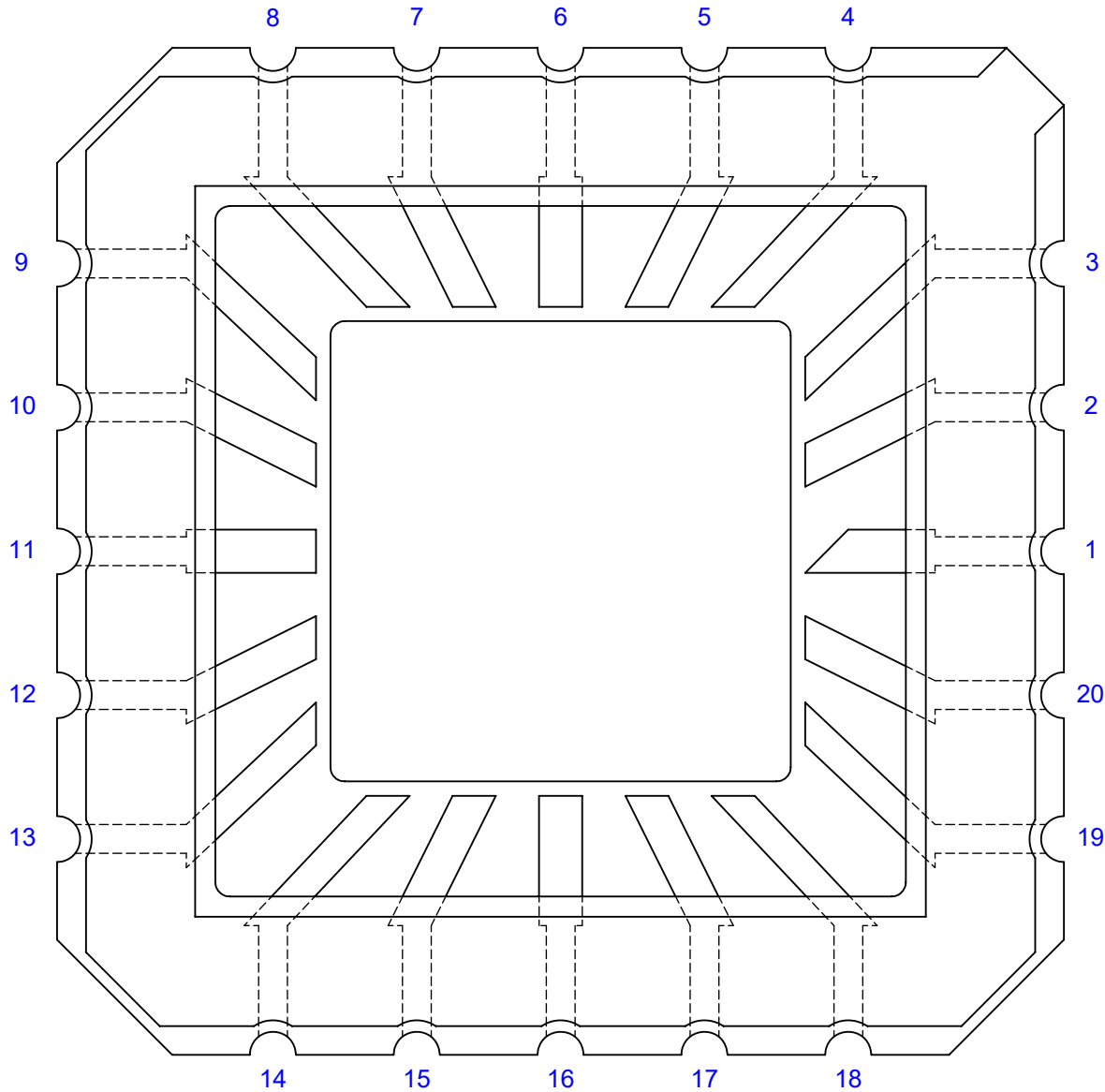
Ni = NONE

Au 20 Micro-Inch (1.5µm) MIN.

3) SEAL RING AND DIE ATTACH SHALL BE ISOLATED FROM ALL LEADS.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	4/16/2022				
ENG M. Hart	4/16/2022	TITLE LCC20B50SQ.35-NM160 NON-MAGNETIC			
MFG		SCALE 10:1	SIZE A	DRAWING NO. 142002	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BOND PAD DIAGRAM



TopLine[®]

TITLE LCC20B50SQ.35-NM160
NON-MAGNETIC

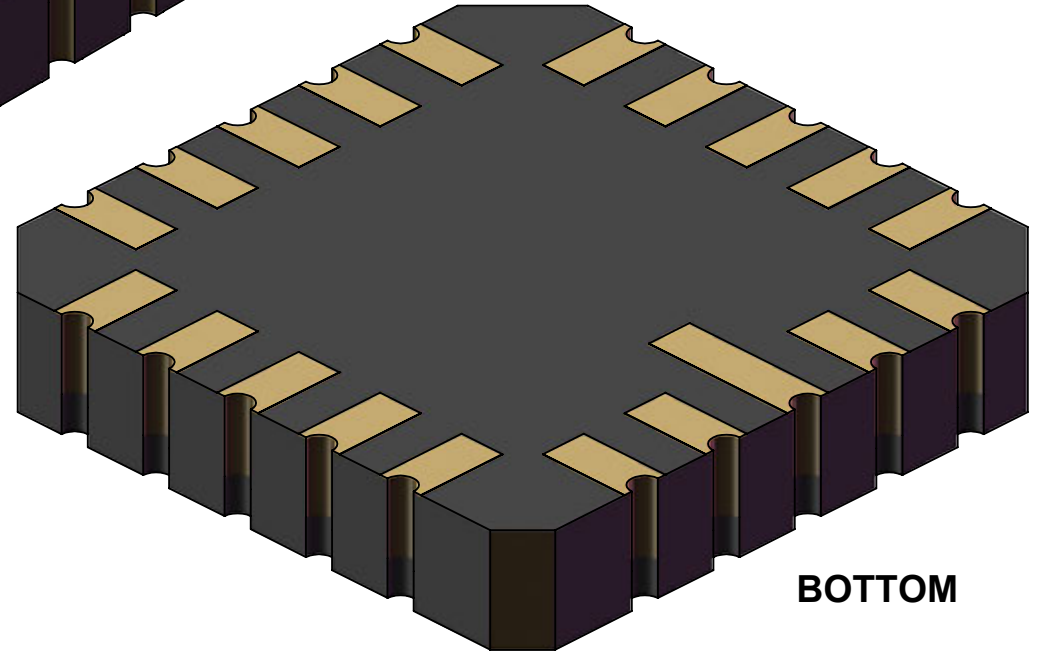
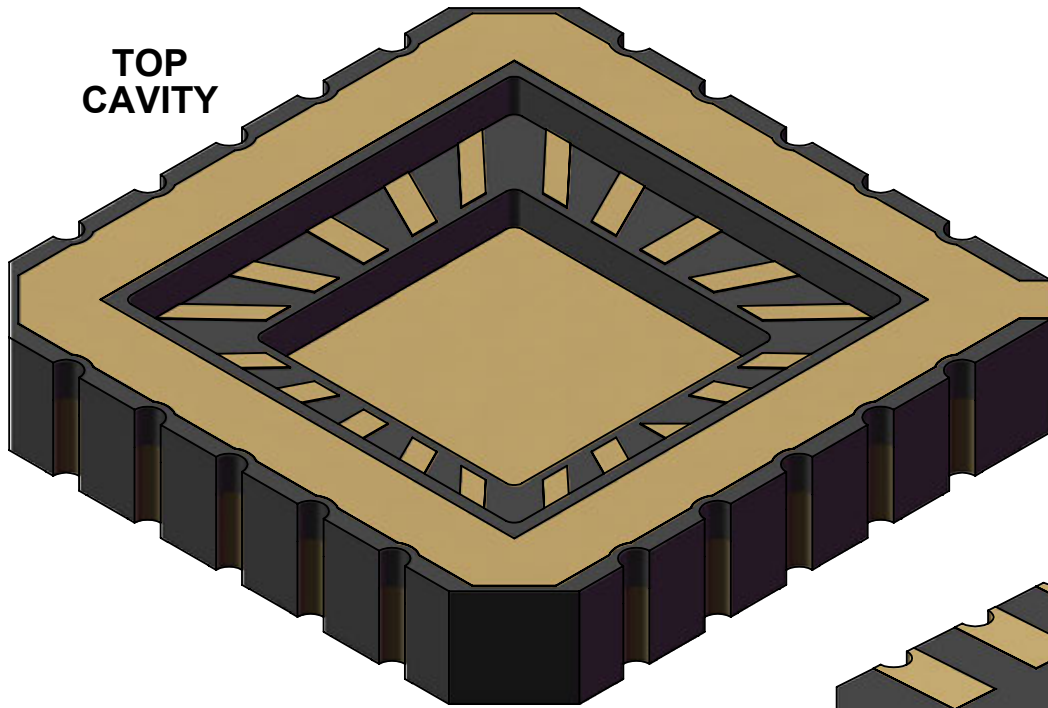
SCALE 16:1	SIZE A	DRAWING NO. 142002	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 4

MODEL

**TOP
CAVITY**



BOTTOM

TopLine®

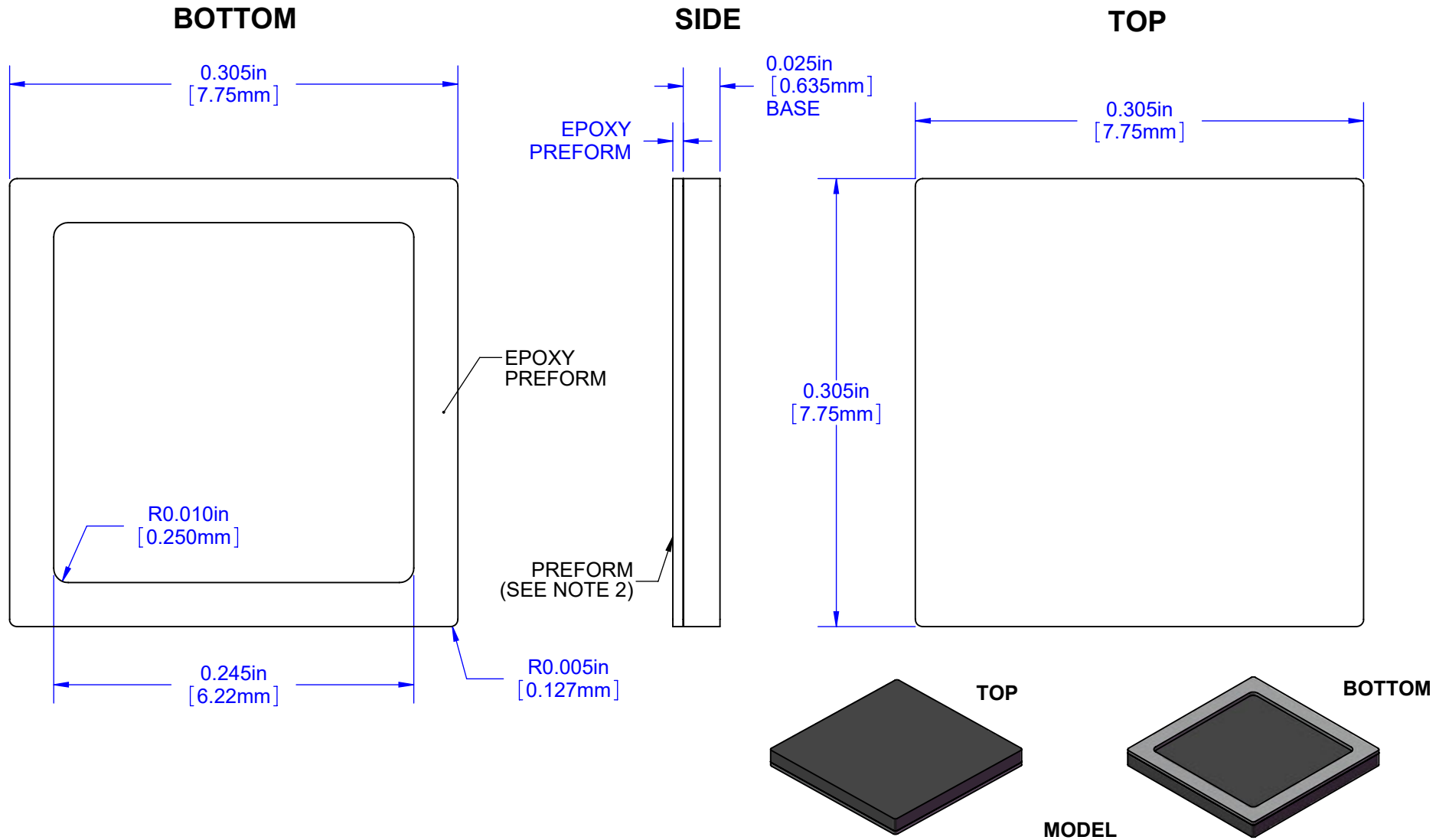
TITLE LCC20B50SQ.35-NM160
NON-MAGNETIC

SCALE 12:1	SIZE A	DRAWING NO. 142002	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 4

CERAMIC LID (OPTIONAL)



NOTES:

1. BASE MATERIAL: BLACK CERAMIC Al₂O₃.
2. Epoxy Preform (B-STAGE) Thickness: 0.003~0.007in [0.076~0.18mm].
3. TOLERANCE: ±0.005in (0.127mm).

TopLine®			
TITLE B-CLID-305-A CERAMIC LID WITH EPOXY PREFORM			
SCALE 10:1	SIZE A	DRAWING NO. 142002	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	